

■ DESCRIPTION

The SMC4923DM uses trench MOSFET technology. Provides extremely low $R_{DS(ON)}$, Low resistance package and excellent fast switching performance. This device is ideal for efficient and fast switching applications.

■ PART NUMBER INFORMATION

SMC 4923D M - TR G

a : Company name.

b : Product Serial number.

c : Package code M:SOP-8

d : Handling code TR:Tape&Reel

e : Green produce code G:RoHS Compliant

■ FEATURES

$V_{DS}=-30V, I_D=-9.2A$

$R_{DS(ON)}=11m\Omega(Typ.) @ V_{GS}=-20V$

$R_{DS(ON)}=12m\Omega(Typ.) @ V_{GS}=-10V$

$R_{DS(ON)}=15m\Omega(Typ.) @ V_{GS}=-4.5V$

◆Fast switch

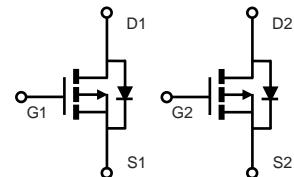
◆High power and current handling capability

■ APPLICATIONS

◆High Frequency Point-of-Load Synchronous

◆DC-DC Power System

◆Load Switch



SOP-8

■ ABSOLUTE MAXIMUM RATINGS ($T_A=25^\circ C$ Unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DSS}	Drain-Source Voltage	-30	V
V_{GSS}	Gate-Source Voltage	± 25	V
I_D	Continuous Drain Current ($V_{GS}=-10V$)	$T_A=25^\circ C$ $T_A=70^\circ C$	-9.2 -7.3
I_{DM}	Pulsed Drain Current ^B	-36.8	A
I_{AS}	Single Pulse Avalanche Current ^B	-30	A
E_{AS}	Single Pulse Avalanche energy L=0.1mH ^B	45	mJ
P_D	Power Dissipation ^A	$T_A=25^\circ C$ $T_A=70^\circ C$	2 1.3
T_J	Operation Junction Temperature	-55/150	°C
T_{STG}	Storage Temperature Range	-55/150	°C

■ THERMAL RESISTANCE

Symbol	Parameter	Typ	Max	Units
$R_{\theta JA}$	Thermal Resistance Junction to Ambient ^A $t \leq 10s$		62	°C/W
	Thermal Resistance Junction to Ambient ^{AC} Steady-State		90	

ELECTRICAL CHARACTERISTICS($T_A=25^\circ\text{C}$ Unless otherwise noted)

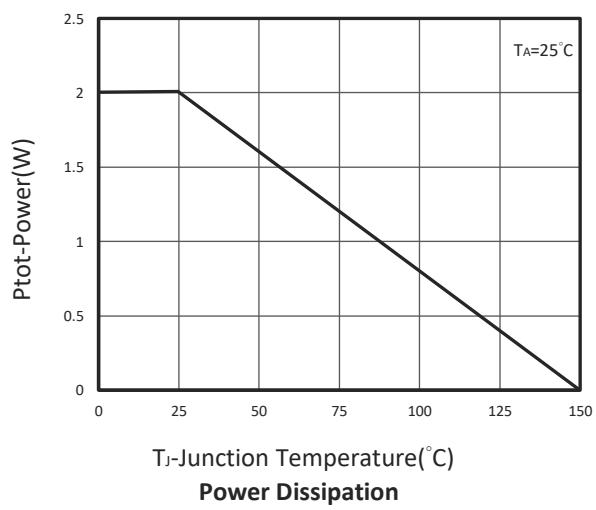
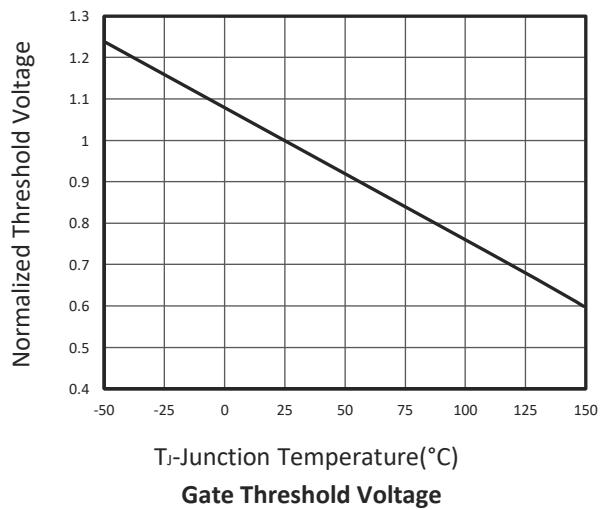
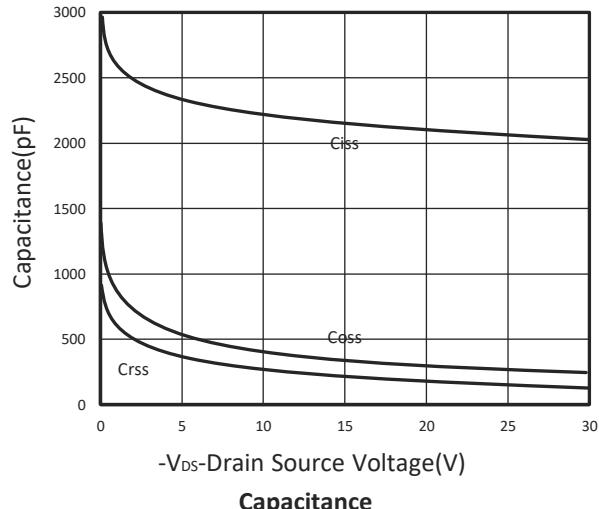
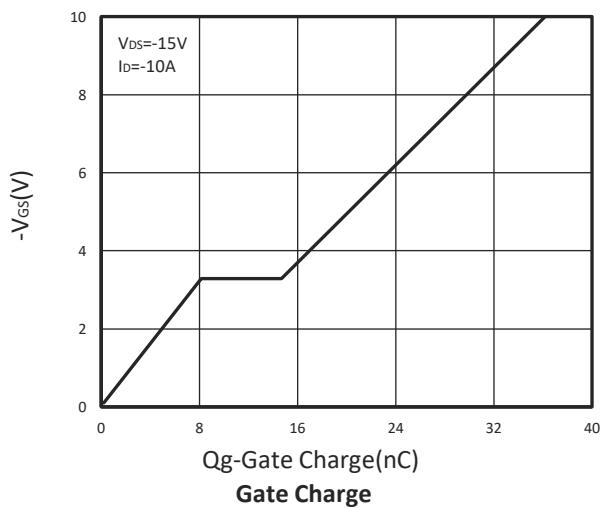
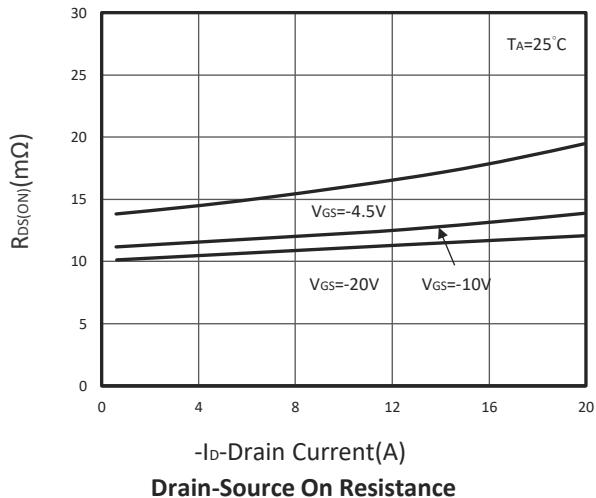
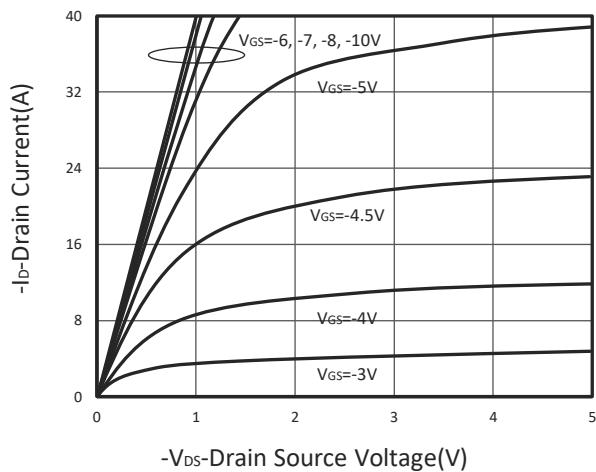
Symbol	Parameter	Condition	Min	Typ	Max	Unit	
Static Parameters							
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=-250\mu\text{A}$	-30			V	
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu\text{A}$	-1	-1.6	-2.5	V	
I_{GSS}	Gate Leakage Current	$V_{DS}=0\text{V}, V_{GS}=\pm 25\text{V}$			± 100	nA	
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-30\text{V}, V_{GS}=0\text{V}, T_J=25^\circ\text{C}$		-1		μA	
		$V_{DS}=-24\text{V}, V_{GS}=0\text{V}, T_J=75^\circ\text{C}$			-10		
$R_{DS(\text{ON})}$	Drain-source On-Resistance ^D	$V_{GS}=-20\text{V}, I_D=-9.2\text{A}$		11	13	$\text{m}\Omega$	
		$V_{GS}=-10\text{V}, I_D=-9.2\text{A}$		12	15		
		$V_{GS}=-4.5\text{V}, I_D=-6\text{A}$		15	19		
G_f	Forward Transconductance	$V_{DS}=-10\text{V}, I_D=-10\text{A}$		12.5		S	
Diode Characteristics							
V_{SD}	Diode Forward Voltage ^D	$I_S=-1\text{A}, V_{GS}=0\text{V}$			-1	V	
I_S	Diode Continuous Forward Current				-9	A	
t_{rr}	Reverse Recovery Time	$I_S=-10\text{A}, dI/dt=100\text{A}/\mu\text{s}$		13.8		ns	
Q_{rr}	Reverse Recovery Charge			11.6		nC	
Dynamic and Switching Parameters^E							
Q_g	Total Gate Charge	$V_{DS}=-15\text{V}, V_{GS}=-10\text{V}$ $I_D=-10\text{A}$		36	48.6	nC	
Q_g	Total Gate Charge (4.5V)			18	24.3		
Q_{gs}	Gate-Source Charge			8.1	10.9		
Q_{gd}	Gate-Drain Charge			6.8	9.2		
C_{iss}	Input Capacitance	$V_{DS}=-15\text{V}, V_{GS}=0\text{V}, f=1\text{MHz}$		2150		pF	
C_{oss}	Output Capacitance			298			
C_{rss}	Reverse Transfer Capacitance			135			
R_g	Gate Resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, F=1\text{MHz}$		8.8		Ω	
$t_{d(on)}$	Turn-On Time	$V_{DD}=-15\text{V}, V_{GEN}=-10\text{V}$ $R_G=3.3\Omega, I_D=-1\text{A}$		7.7	15	nS	
				57.8	129		
$t_{d(off)}$	Turn-Off Time			57.5	109		
				21.3	40		

Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged.

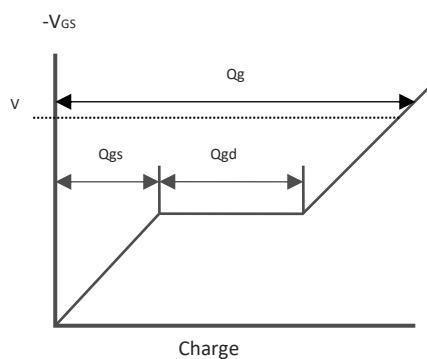
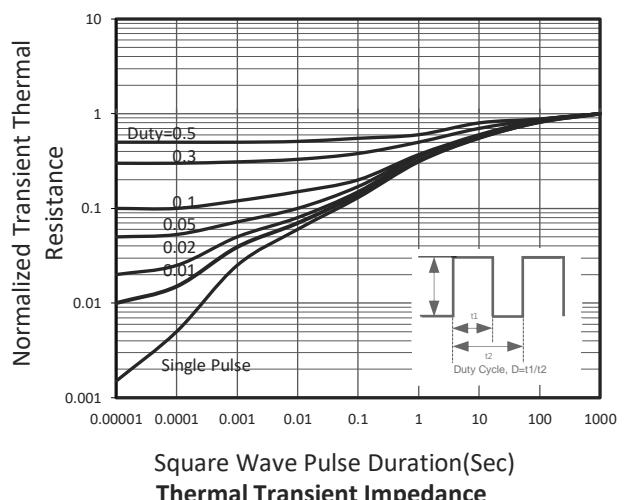
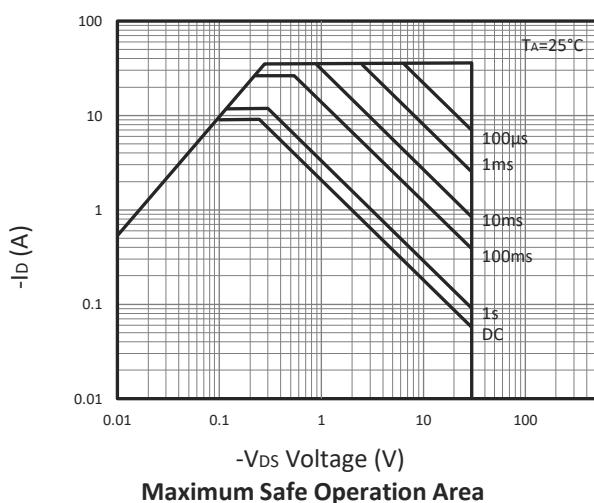
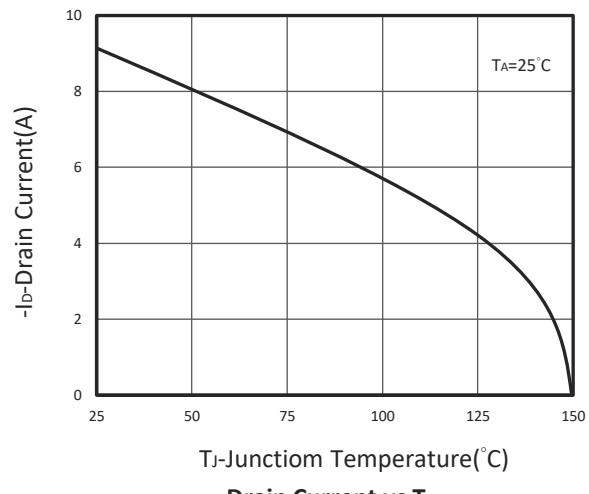
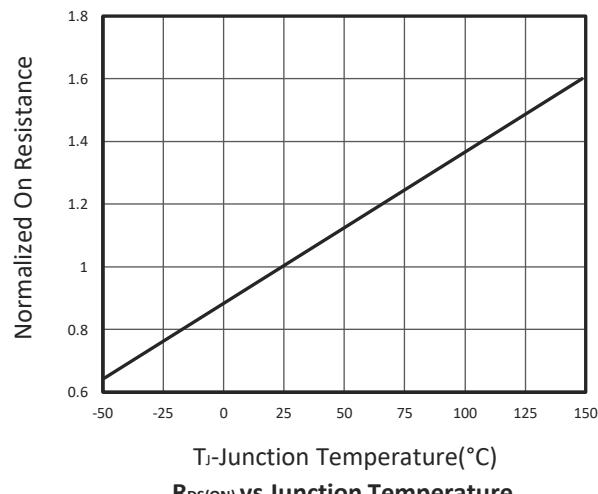
- A. Surface mounted on FR4 board using 1 in² pad size.
- B. Pulsed width limited by maximum junction temperature, $T_J(\text{MAX})=150^\circ\text{C}$ (initial temperature $T_J=25^\circ\text{C}$).
- C. Using $\leq 10\text{s}$ junction-to-ambient thermal resistance is base on $T_J(\text{MAX})=150^\circ\text{C}$.
- D. Pulse test width $\leq 300\mu\text{s}$ and duty cycle $\leq 2\%$.
- E. Guaranteed by design, not subject to production testing.

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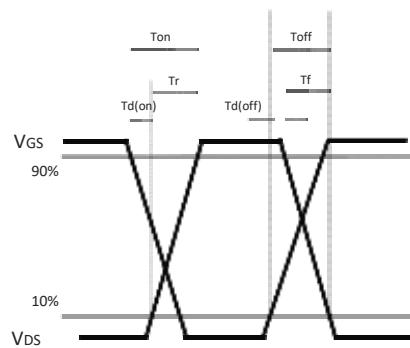
■ TYPICAL CHARACTERISTICS



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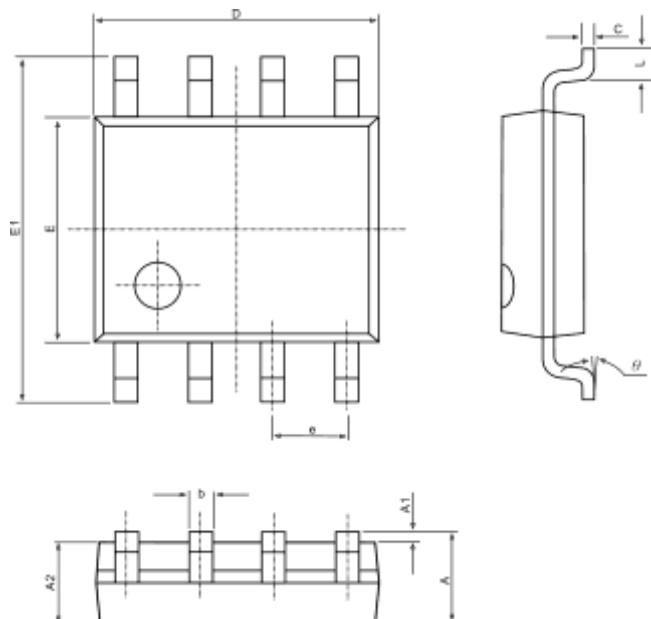


Gate Charge Waveform

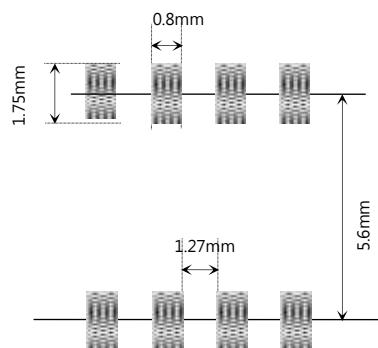


Switching Time Waveform

SOP-8 PACKAGE DIMENSIONS



Recommended Land Pattern



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.300	1.500	0.051	0.059
b	0.390	0.490	0.015	0.019
c	0.200	0.250	0.008	0.010
D	4.800	5.100	0.189	0.201
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270 BSC		0.050 BSC	
L	0.500	0.800	0.020	0.031
Θ	0°	8°	0°	8°